Product/Process Change Notice - PCN 16_0280 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

PCN Title: Addition of ASE Korea as an Alternate Assembly Site and STATS ChipPAC Singapore as an Alternate Test Site for ADA4930-1 LFCSP Part

Publication Date: 22-Feb-2017

Effectivity Date: 23-May-2017 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release

Description Of Change

ADI is adding ASE Korea as an alternate assembly site and STATS ChipPAC Singapore as an alternate test site for ADA4930-1 LFCSP product.
ADI has qualified ASE Korea's BOM(Bill of Materials). Mold compound is changing from Hitachi CEL 9220HF13 to Sumitomo G770LYT. See BOM attachment for details.
The package outline exposed pad dimensions are changing for 3x3mm 16LD. See POD attachment for details.

Reason For Change

ADI's current Assembly supplier STATS ChipPAC China is relocating their factory by end of September 2017.
In this regard, Addition of ASE Korea as an Alternate Assembly Site and STATS ChipPAC Singapore as an Alternate Test Site for ADA4930-1 LFCSP Part will ensure continuous supply of products.
ADI's assembly subcontractors manufacture products using Analog Devices specified manufacturing flows, materials, process controls and monitors, ensuring the same level of quality and reliability on products they receive from the new site.

Impact of the change (positive or negative) on fit, form, function & reliability

There will be no impact on the form, fit, function and reliability of the devices.

Product Identification *(this section will describe how to identify the changed material)*

The parts that will be assembled and tested from the alternate site will be identified by assembly lot and the country of origin.

Summary of Supporting Information

Qualification is in process per AEC-Q100, Stress Test Qualification for Integrated Circuits. See attached qualification plan.
Test correlation and validation has been performed per ADI's standard product site to site change correlation procedure. See attached Test Correlation Report.

Comments

During addition of new assembly and/or test site, products will be assembled/or tested from either current or alternate Assembly and/or test Site. The customers may receive products that are assembled at AEK & tested at SCC and/or assembled at SCC & tested at STA.
Applies for all packing/reel options.

Supporting Documents

Attachment 1: Type: Qualification Plan

ADI_PCN_16_0280_Rev_-_Qualification Plan for 24L LFCSP.pdf

Attachment 2: Type: Qualification Plan

ADI_PCN_16_0280_Rev_-_Qualification Plan for 48L LFCSP.pdf

Attachment 3: Type: Detailed Change Description

ADI_PCN_16_0280_Rev_-_BOM Change Description.pptx

Attachment 4: Type: Detailed Change Description

ADI_PCN_16_0280_Rev_-_POD Change Description.pptx

Attachment 5: Type: Test Correlation Report

ADI_PCN_16_0280_Rev_-_TEST CORRELATION REPORT.xlsx

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.					
Americas:	PCN_Americas@analog.com	**Europe:**	PCN_Europe@analog.com	**Japan:**	PCN_Japan@analog.com
				Rest of Asia:	PCN_ROA@analog.com

Appendix A - Affected ADI Models				
Added Parts On This Revision - Product Family / Model Number (3)				
ADA4930-1 / ADA4930-1SCPZ-EPR2	ADA4930-1 / ADA4930-1SCPZ-EPR7	ADA4930-1 / ADA4930-1SCPZ-EPRL		

Appendix B - Revision History			
Rev	**Publish Date**	**Effectivity Date**	**Rev Description**
Rev. -	22-Feb-2017	23-May-2017	Initial Release